

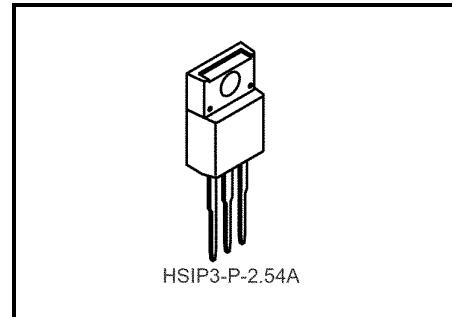
TOSHIBA Bipolar Linear Integrated Circuit Silicon Monolithic

**TA7805S, TA78057S, TA7806S, TA7807S, TA7808S, TA7809S,
TA7810S, TA7812S, TA7815S, TA7818S, TA7820S, TA7824S****Three Terminal Positive Voltage Regulators**

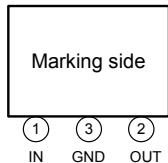
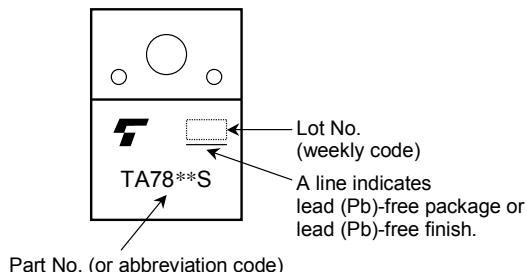
5 V, 5.7 V, 6 V, 7 V, 8 V, 9 V, 10 V, 12 V, 15 V, 18 V, 20 V, 24 V

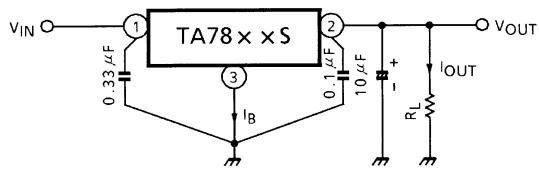
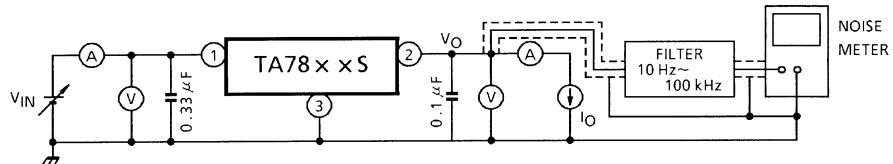
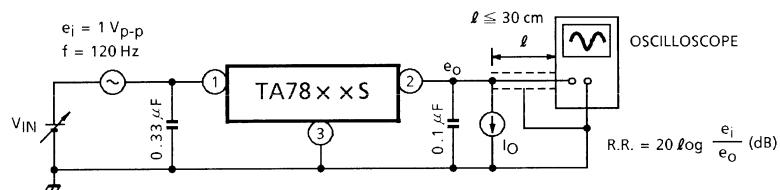
Features

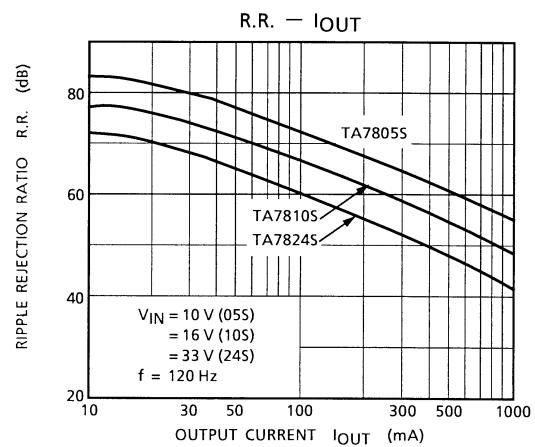
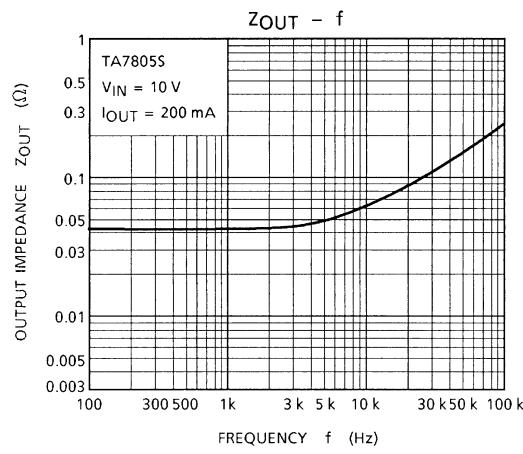
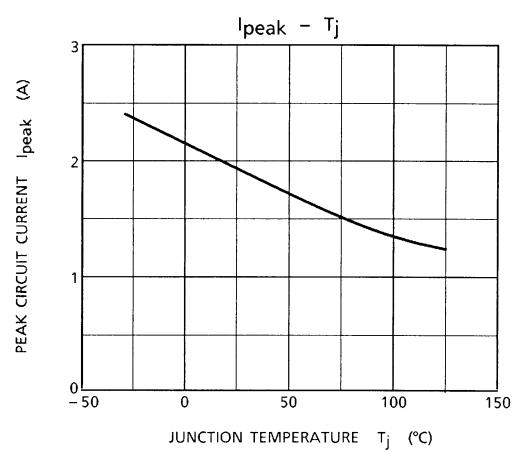
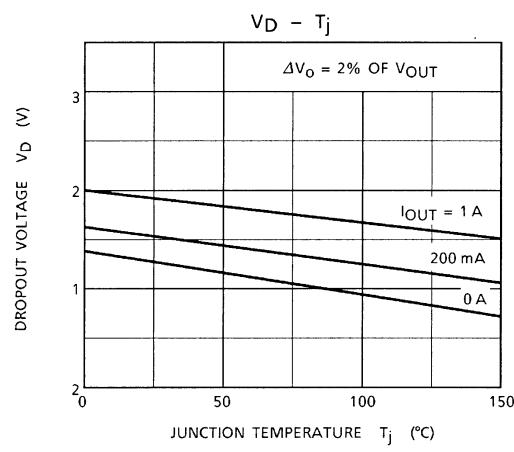
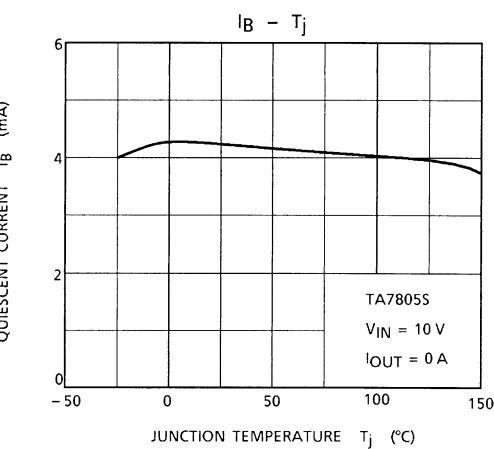
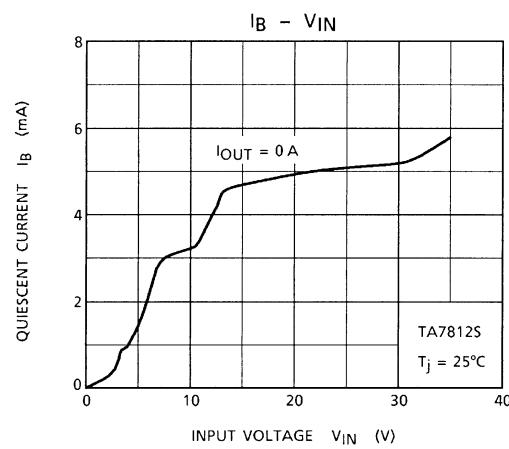
- Suitable for CMOS, TTL, the power supply of other digital ICs
- Internal thermal overload protection
- Internal short circuit current limiting
- Maximum output current of 1 A
- Metal fin (tab) is fully covered with mold resin.
(TO-220 NIS package)

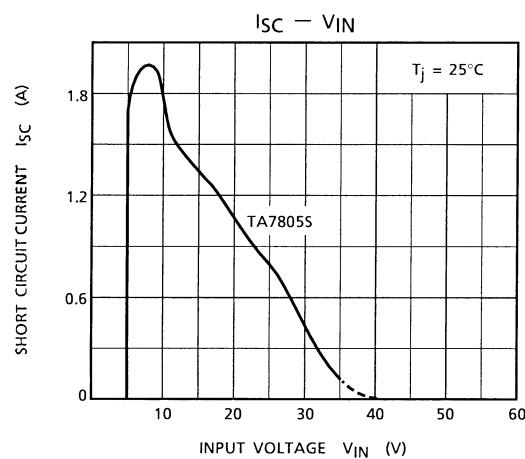


Weight: 1.7 g (typ.)

Pin Assignment**Marking**

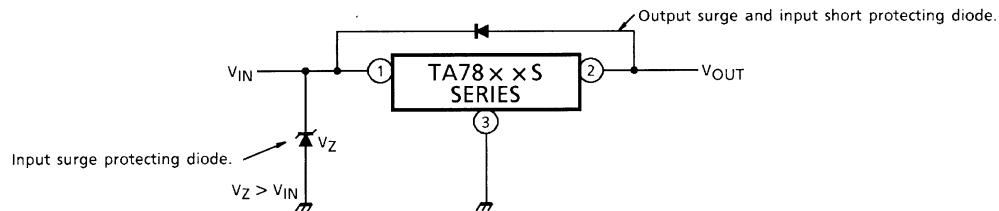
Test Circuit 1/Standard Application Circuit

Test Circuit 2
V_{NO}

Test Circuit 3
R.R.




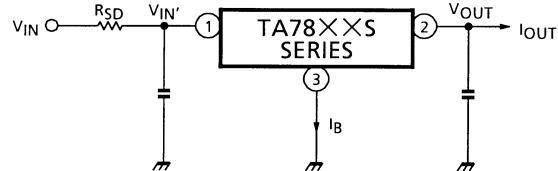


Precautions on Application

- (1) In regard to GND, be careful not to apply a negative voltage to the input/output terminal. Further, special care is necessary in the case of a voltage boost application.
- (2) If a surge voltage exceeding the maximum rating is applied to the input terminal or if a voltage in excess of the input terminal voltage is applied to the output terminal, the circuit may be destroyed. Particular care is necessary in the case of the latter. Circuit destruction may also occur if the input terminal shorts to GND in a state of normal operation, causing the output terminal voltage to exceed the input voltage (GND potential) and the electrical charge of the chemical capacitor connected to the output terminal to flow into the input side. Where these risks exist, take steps such as connecting zener and general silicon diodes to the circuit, as shown in the figure below.



- (3) When the input voltage is too high, the power dissipation of the three-terminal regulator, which is a series regulator, increases, causing the junction temperature to rise. In such a case, it is recommended to reduce the power dissipation, and hence the junction temperature, by inserting a power-limiting resistor R_{SD} in the input terminal.



The power dissipation P_D of the IC is expressed in the following equation.

$$P_D = (V_{IN'} - V_{OUT}) \cdot I_{OUT} + V_{IN'} \cdot I_B$$

Reducing $V_{IN'}$ below the lowest voltage necessary for the IC will cause ripple, deterioration in output regulation and, in certain circumstances, parasitic oscillation.

To determine the resistance value of R_{SD} , design with a margin, referring to the following equation.

$$R_{SD} < \frac{V_{IN} - V_{IN'}}{I_{OUT} + I_B}$$

- (4) Be sure to connect a capacitor near the input terminal and output terminal between both terminals and GND. The capacitances should be determined experimentally because they depend on PCB patterns. In particular, adequate investigation should be made to ensure there is no problem even in high or low temperatures

(5) Installation of IC for power supply

To obtain high reliability on the heat sink design of a regulator IC, it is generally required to derate more than 20% of maximum junction temperature (T_j max).

Further, full consideration should be given to the installation of a heat sink in the IC.

(a) Heat sink design

The thermal resistance of the IC itself is required from the viewpoint of the design of elements, but the thermal resistance from the IC package to the open air varies with the contact thermal resistance.

Table 1 shows how much the value of the contact thermal resistance ($\theta_c + \theta_s$) is changed by insulating sheet (mica) and heat sink grease.

Table 1

Unit: °C/W

Package	Model No.	Torque	Mica	$\theta_c + \theta_s$
TO-220NIS	TA78xxS	0.6 N·m	Not provided	0.4~0.6 (1.0~1.5)

The figures given in parentheses denote the values for when there is no grease.

The regulator IC package serves as GND, therefore of the value for when there is "no mica" should be used.

(b) Silicone grease

In the design of a circuit not exceeding the maximum rating, grease should be used if possible. If it is necessary to reduce the contact thermal resistance for the sake of circuit design, the following methods are recommended.

If using grease, use YG6260 (TOSHIBA SILICON CORPORATION).

(c) Torque

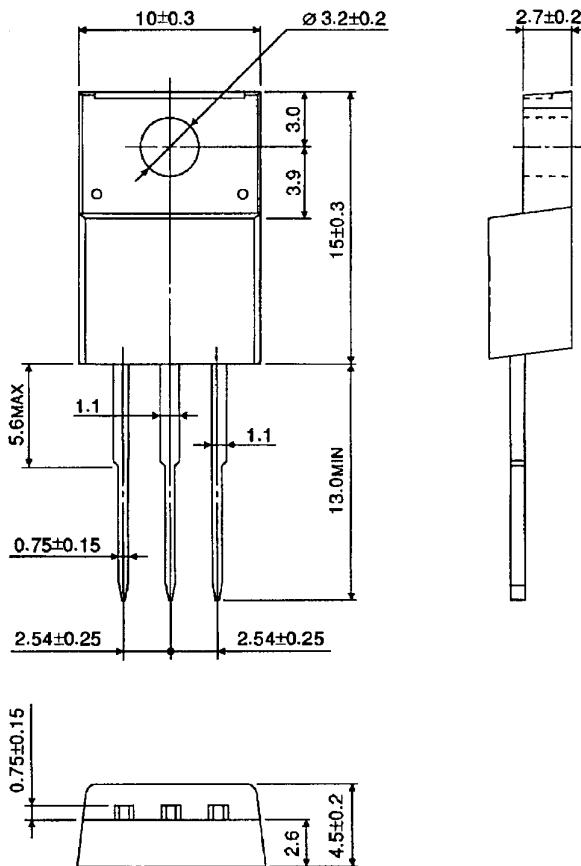
When installing the IC on a heat sink or the like, tighten the IC with a torque of less than the rated value. Tightening in excess of the rated value may cause internal elements of the IC to be adversely affected. Therefore, great care should be given to the installation procedure.

Further, if polycarbonate screws are used, the torque causes a change with the passage of time, which may lessen the effect of radiation.

Package Dimensions

HSIP3-P-2.54A

Unit: mm



Weight: 1.7 g (typ.)

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